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Intel - EPM7512AETC144-7 Datasheet



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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	10000
Number of I/O	120
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7512aetc144-7

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MAX 7000A devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000A architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000A devices contain from 32 to 512 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and highspeed parallel expander product terms, providing up to 32 product terms per macrocell.

MAX 7000A devices provide programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000A devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000A devices can be set for 2.5 V or 3.3 V, and all input pins are 2.5-V, 3.3-V, and 5.0-V tolerant, allowing MAX 7000A devices to be used in mixed-voltage systems.

MAX 7000A devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

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For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

Functional Description

The MAX 7000A architecture includes the following elements:

- Logic array blocks (LABs)
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000A architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of MAX 7000A devices.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- Global clock signal. This mode achieves the fastest clock-to-output performance.
- Global clock signal enabled by an active-high clock enable. A clock enable is generated by a product term. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- Array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

Two global clock signals are available in MAX 7000A devices. As shown in Figure 1, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figure 2, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear from the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in a MAX 7000AE device may be set to either a high or low state. This power-up state is specified at design entry. Upon power-up, each register in EPM7128A and EPM7256A devices are set to a low state.

All MAX 7000A I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast (as low as 2.5 ns) input setup time.

Expander Product Terms

Although most logic functions can be implemented with the five product terms available in each macrocell, more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources. However, the MAX 7000A architecture also offers both shareable and parallel expander product terms that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay (t_{SEXP}) is incurred when shareable expanders are used. Figure 3 shows how shareable expanders can feed multiple macrocells.



Shareable expanders can be shared by any or all macrocells in an LAB.



Figure 5. MAX 7000A PIA Routing



While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000A PIA has a predictable delay. The PIA makes a design's timing performance easy to predict.

I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC} . Figure 6 shows the I/O control block for MAX 7000A devices. The I/O control block has 6 or 10 global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

In-System Programmability

MAX 7000A devices can be programmed in-system via an industrystandard 4-pin IEEE Std. 1149.1 (JTAG) interface. ISP offers quick, efficient iterations during design development and debugging cycles. The MAX 7000A architecture internally generates the high programming voltages required to program EEPROM cells, allowing in-system programming with only a single 3.3-V power supply. During in-system programming, the I/O pins are tri-stated and weakly pulled-up to eliminate board conflicts. The pull-up value is nominally 50 k Ω .

MAX 7000AE devices have an enhanced ISP algorithm for faster programming. These devices also offer an ISP_Done bit that provides safe operation when in-system programming is interrupted. This ISP_Done bit, which is the last bit programmed, prevents all I/O pins from driving until the bit is programmed. This feature is only available in EPM7032AE, EPM7064AE, EPM7128AE, EPM7256AE, and EPM7512AE devices.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a PCB with standard pick-and-place equipment before they are programmed. MAX 7000A devices can be programmed by downloading the information via in-circuit testers, embedded processors, the Altera MasterBlaster serial/USB communications cable, ByteBlasterMV parallel port download cable, and BitBlaster serial download cable. Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling. MAX 7000A devices can be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. A constant algorithm uses a predefined (non-adaptive) programming sequence that does not take advantage of adaptive algorithm programming time improvements. Some in-circuit testers cannot program using an adaptive algorithm. Therefore, a constant algorithm must be used. MAX 7000AE devices can be programmed with either an adaptive or constant (non-adaptive) algorithm. EPM7128A and EPM7256A device can only be programmed with an adaptive algorithm; users programming these two devices on platforms that cannot use an adaptive algorithm should use EPM7128AE and EPM7256AE devices.

The Jam Standard Test and Programming Language (STAPL), JEDEC standard JESD 71, can be used to program MAX 7000A devices with incircuit testers, PCs, or embedded processors.



For more information on using the Jam STAPL language, see *Application Note 88 (Using the Jam Language for ISP & ICR via an Embedded Processor)* and *Application Note 122 (Using Jam STAPL for ISP & ICR via an Embedded Processor)*.

ISP circuitry in MAX 7000AE devices is compliant with the IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000A device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- 1. *Enter ISP*. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- 4. *Program*. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- 5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. *Exit ISP*. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

The programming times described in Tables 5 through 7 are associated with the worst-case method using the enhanced ISP algorithm.

Device	Progra	mming	Stand-Alone Verification			
	t _{PPULSE} (s)	Cycle _{PTCK}	t _{VPULSE} (s)	Cycle _{VTCK}		
EPM7032AE	2.00	55,000	0.002	18,000		
EPM7064AE	2.00	105,000	0.002	35,000		
EPM7128AE	2.00	205,000	0.002	68,000		
EPM7256AE	2.00	447,000	0.002	149,000		
EPM7512AE	2.00	890,000	0.002	297,000		
EPM7128A (1)	5.11	832,000	0.03	528,000		
EPM7256A (1)	6.43	1,603,000	0.03	1,024,000		

Tables 6 and 7 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 6. MAX 7000A In-System Programming Times for Different Test Clock Frequencies												
Device		f _{TCK}										
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz				
EPM7032AE	2.01	2.01	2.03	2.06	2.11	2.28	2.55	3.10	S			
EPM7064AE	2.01	2.02	2.05	2.11	2.21	2.53	3.05	4.10	s			
EPM7128AE	2.02	2.04	2.10	2.21	2.41	3.03	4.05	6.10	s			
EPM7256AE	2.05	2.09	2.23	2.45	2.90	4.24	6.47	10.94	s			
EPM7512AE	2.09	2.18	2.45	2.89	3.78	6.45	10.90	19.80	s			
EPM7128A (1)	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	S			
EPM7256A (1)	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	S			

Table 8. MAX 7000A	JIAG Instructions
JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins
BYPASS	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation
IDCODE	Selects the IDCODE register and places it between the TDI and TDO pins, allowing the IDCODE to be serially shifted out of TDO
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE value to be shifted out of TDO. The USERCODE instruction is available for MAX 7000AE devices only
UESCODE	These instructions select the user electronic signature (UESCODE) and allow the UESCODE to be shifted out of TDO. UESCODE instructions are available for EPM7128A and EPM7256A devices only.
ISP Instructions	These instructions are used when programming MAX 7000A devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, or BitBlaster download cable, or using a Jam STAPL File, JBC File, or SVF File via an embedded processor or test equipment.

Table 8. MAX 7000A JTAG Instructions

Figure 11. MAX 7000A Timing Model



The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 12 shows the timing relationship between internal and external delay parameters.



See *Application Note 94 (Understanding MAX 7000 Timing)* for more information.

Symbol	Parameter	Conditions	Speed Grade								
			-4	4	-	7	-10				
			Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non- registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns		
t _{PD2}	I/O input to non- registered output	C1 = 35 pF (2)		4.5		7.5		10.0	ns		
t _{SU}	Global clock setup time	(2)	2.8		4.7		6.2		ns		
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.1	1.0	5.1	1.0	7.0	ns		
t _{CH}	Global clock high time		2.0		3.0		4.0		ns		
t _{CL}	Global clock low time		2.0		3.0		4.0		ns		
t _{ASU}	Array clock setup time	(2)	1.6		2.6		3.6		ns		
t _{AH}	Array clock hold time	(2)	0.3		0.4		0.6		ns		
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.3	1.0	7.2	1.0	9.6	ns		
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns		
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns		
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns		
t _{CNT}	Minimum global clock period	(2)		4.5		7.4		10.0	ns		
f _{CNT}	Maximum internal global clock frequency	(2), (4)	222.2		135.1		100.0		MHz		
t _{acnt}	Minimum array clock period	(2)		4.5		7.4		10.0	ns		
f _{acnt}	Maximum internal array clock frequency	(2), (4)	222.2		135.1		100.0		MHz		

Symbol	Parameter	Conditions	Speed Grade							
			-;	5	-	7	-1	0		
			Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non- registered output	C1 = 35 pF (2)		5.5		7.5		10	ns	
t _{PD2}	I/O input to non- registered output	C1 = 35 pF (2)		5.5		7.5		10	ns	
t _{SU}	Global clock setup time	(2)	3.9		5.2		6.9		ns	
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.5	1.0	4.8	1.0	6.4	ns	
t _{CH}	Global clock high time		2.0		3.0		4.0		ns	
t _{CL}	Global clock low time		2.0		3.0		4.0		ns	
t _{ASU}	Array clock setup time	(2)	2.0		2.7		3.6		ns	
t _{AH}	Array clock hold time	(2)	0.2		0.3		0.5		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	5.4	1.0	7.3	1.0	9.7	ns	
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns	
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns	
t _{CNT}	Minimum global clock period	(2)		5.8		7.9		10.5	ns	
f _{CNT}	Maximum internal global clock frequency	(2), (4)	172.4		126.6		95.2		MHz	
t _{acnt}	Minimum array clock period	(2)		5.8		7.9		10.5	ns	
f _{acnt}	Maximum internal array clock frequency	(2), (4)	172.4		126.6		95.2		MHz	

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Symbol	Parameter	Conditions	Speed Grade						
			-5 -			7		10	
			Min	Max	Min	Max	Min	Max	1
t _{IN}	Input pad and buffer delay			0.7		0.9		1.2	ns
t _{IO}	I/O input pad and buffer delay			0.7		0.9		1.2	ns
t _{FIN}	Fast input delay			2.4		2.9		3.4	ns
t _{SEXP}	Shared expander delay			2.1		2.8		3.7	ns
t _{PEXP}	Parallel expander delay			0.3		0.5		0.6	ns
t _{LAD}	Logic array delay			1.7		2.2		2.8	ns
t _{LAC}	Logic control array delay			0.8		1.0		1.3	ns
t _{IOE}	Internal output enable delay			0.0		0.0		0.0	ns
t _{OD1}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		0.9		1.2		1.6	ns
t _{OD2}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 2.5 V$	C1 = 35 pF (5)		1.4		1.7		2.1	ns
t _{OD3}	Output buffer and pad delay, slow slew rate = on $V_{CCIO} = 2.5 V \text{ or } 3.3 V$	C1 = 35 pF		5.9		6.2		6.6	ns
t _{ZX1}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5 V$	C1 = 35 pF (5)		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3 V$	C1 = 35 pF		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0	ns
t _{SU}	Register setup time		1.5		2.1		2.9		ns
t _H	Register hold time		0.7		0.9		1.2		ns
t _{FSU}	Register setup time of fast input		1.1		1.6		1.6		ns
t _{FH}	Register hold time of fast input		1.4		1.4		1.4		ns
t _{RD}	Register delay			0.9		1.2		1.6	ns
t _{COMB}	Combinatorial delay			0.5		0.8		1.2	ns

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Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	7	-	10	-12		1
			Min	Max	Min	Max	Min	Max	
t _{IC}	Array clock delay			1.8		2.3		2.9	ns
t _{EN}	Register enable time			1.0		1.3		1.7	ns
t _{GLOB}	Global control delay			1.7		2.2		2.7	ns
t _{PRE}	Register preset time			1.0		1.4		1.7	ns
t _{CLR}	Register clear time			1.0		1.4		1.7	ns
t _{PIA}	PIA delay	(2)		3.0		4.0		4.8	ns
t _{LPA}	Low-power adder	(6)		4.5		5.0		5.0	ns

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	-6		-7		10	-12]
			Min	Мах	Min	Мах	Min	Мах	Min	Max	1
t _{RD}	Register delay			1.7		2.1		2.8		3.3	ns
t _{COMB}	Combinatorial delay			1.7		2.1		2.8		3.3	ns
t _{IC}	Array clock delay			2.4		3.0		4.1		4.9	ns
t _{EN}	Register enable time			2.4		3.0		4.1		4.9	ns
t _{GLOB}	Global control delay			1.0		1.2		1.7		2.0	ns
t _{PRE}	Register preset time			3.1		3.9		5.2		6.2	ns
t _{CLR}	Register clear time			3.1		3.9		5.2		6.2	ns
t _{PIA}	PIA delay	(2)		0.9		1.1		1.5		1.8	ns
t _{LPA}	Low-power adder	(6)		11.0		10.0		10.0		10.0	ns

Figure 13 shows the typical supply current versus frequency for MAX 7000A devices.





EPM7128A & EPM7128AE



Figure 17. 100-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.



Figure 18. 100-Pin FineLine BGA Package Pin-Out Diagram



Figure 19. 144-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.



Figure 20. 169-Pin Ultra FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.



Figure 21. 208-Pin PQFP Package Pin-Out Diagram

Package outline not drawn to scale.



Figure 23. 256-Pin FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.



Revision History

The information contained in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5 supersedes information published in previous versions.

Version 4.5

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.5:

■ Updated text in the "Power Sequencing & Hot-Socketing" section.

Version 4.4

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.4:

- Added Tables 5 through 7.
 - Added "Programming Sequence" on page 17 and "Programming Times" on page 18.